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**DSP
Microcomputer
ADSP-21065L**

Preliminary Technical Data

1.0 Purpose

The purpose of this document is to provide package characteristics and data for the ADSP-21065L 196-ball mini BGA.

2.0 Package Data

The ADSP-21065L is packaged in a 196 ball, 15mm x 15mm plastic package.

2.1 Electrical Characteristics

The electrical characteristics found in the ADSP-21065L Final Data Sheet (Rev. 0, April, 1999) can be used for the ADSP-21065LKCA-240X. Note that these numbers are PRELIMINARY for this package only at this time.

2.2 Thermal Characteristics

TBD

2.3 Package Mechanics and Pin-list

Follows

ADSP-21065L Preliminary Data Sheet

April 1999

For current information contact Analog Devices at (781) 461-3881

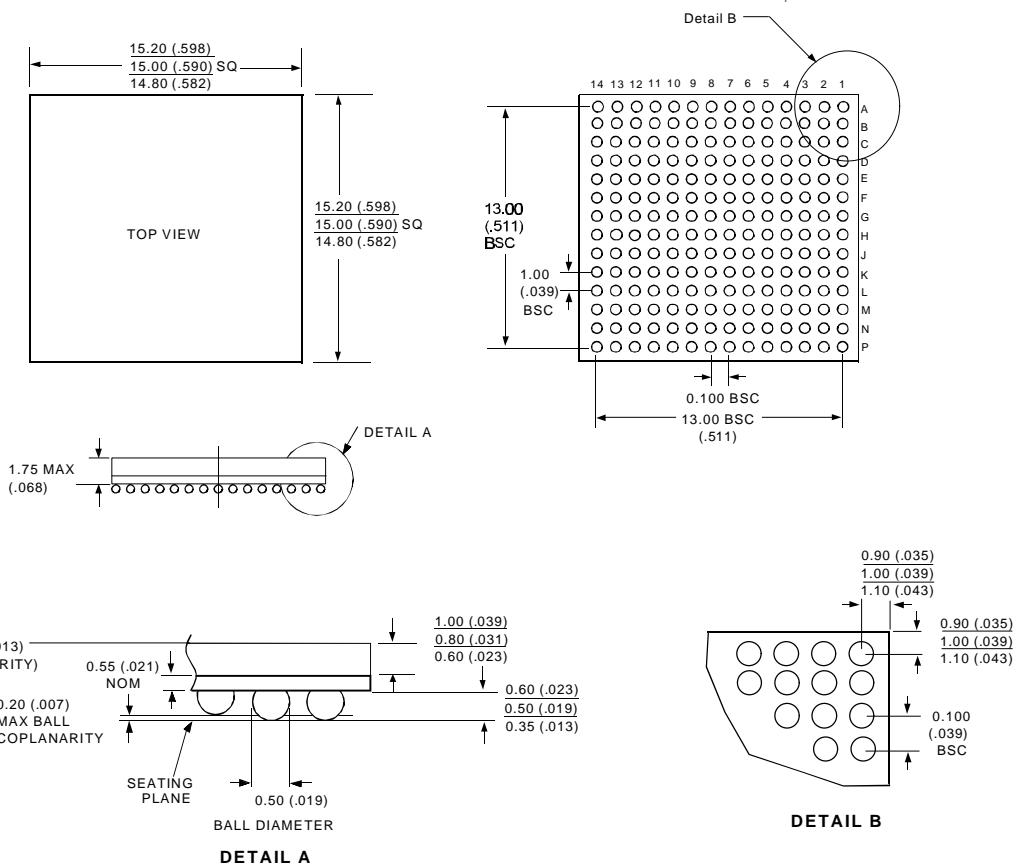
ADSP-2165L Mini-BGA Package Pinout

BALL #	NAME	BALL#	NAME	BALL #	NAME	BALL #	NAME	BALL #	NAME
A1	NC1	B1	DR0A	C1	TCLK0	D1	RCLK1	E1	TFS1
A2	NC2	B2	RFS0	C2	RCLK0	D2	TFS0	E2	DT0B
A3	FLAG2	B3	IRQ0	C3	IRQ2	D3	DR0B	E3	DT0A
A4	ADDR0	B4	FLAG0	C4	FLAG3	D4	IRQT	E4	RFS1
A5	ADDR3	B5	ADDR2	C5	ADDR1	D5	FLAG1	E5	VDD
A6	ADDR6	B6	ADDR5	C6	ADDR4	D6	VDD	E6	GND
A7	ADDR7	B7	ADDR9	C7	ADDR10	D7	VDD	E7	GND
A8	ADDR8	B8	ADDR12	C8	ADDR13	D8	VDD	E8	GND
A9	ADDR11	B9	ADDR15	C9	ADDR16	D9	VDD	E9	GND
A10	ADDR14	B10	ADDR19	C10	ADDR20	D10	VDD	E10	VDD
A11	ADDR17	B11	ADDR21	C11	ADDR22	D11	BMS	E11	ID0
A12	ADDR18	B12	ADDR23	C12	RESET	D12	TMS	E12	TDI
A13	NC8	B13	GND	C13	BSEL	D13	TRST	E13	ID1
A14	NC7	B14	TCK	C14	TDO	D14	EMU	E14	FLAG4
F1	TCLK1	G1	PWM_EVENT1	H1	PWM_EVENT0	J1	CLKIN	K1	DMART
F2	DR1B	G2	DT1B	H2	BRT	J2	XTAL	K2	SDCLK0
F3	DR1A	G3	DT1A	H3	BR2	J3	SDCLK1	K3	HBR
F4	VDD	G4	VDD	H4	VDD	J4	VDD	K4	SDWE
F5	GND	G5	GND	H5	GND	J5	GND	K5	VDD
F6	GND	G6	GND	H6	GND	J6	GND	K6	GND
F7	GND	G7	GND	H7	GND	J7	GND	K7	GND
F8	GND	G8	GND	H8	GND	J8	GND	K8	GND
F9	GND	G9	GND	H9	GND	J9	GND	K9	GND
F10	GND	G10	GND	H10	GND	J10	GND	K10	VDD
F11	VDD	G11	VDD	H11	VDD	J11	VDD	K11	DATA19
F12	FLAG6	G12	DATA31	H12	DATA28	J12	DATA24	K12	DATA21
F13	FLAG5	G13	DATA30	H13	DATA27	J13	DATA25	K13	DATA20
F14	FLAG7	G14	DATA29	H14	DATA26	J14	DATA23	K14	DATA22
L1	DMAR2	M1	RAS	N1	DQM	P1	NC3		
L2	CAS	M2	SDCKE	N2	HBG	P2	NC4		
L3	SDA10	M3	DMAGT	N3	BMSTR	P3	GND		
L4	DMAG2	M4	CS	N4	SBTS	P4	WR		
L5	VDD	M5	RD	N5	REDY	P5	SW		
L6	VDD	M6	CPA	N6	GND	P6	MS0		
L7	VDD	M7	ACK	N7	MSI	P7	MS2		
L8	VDD	M8	FLAG10	N8	FLAG11	P8	MS3		
L9	VDD	M9	DATA2	N9	DATA1	P9	FLAG9		
L10	DATA8	M10	DATA5	N10	DATA4	P10	FLAG8		
L11	DATA13	M11	DATA9	N11	DATA7	P11	DATA0		
L12	DATA16	M12	DATA12	N12	DATA10	P12	DATA3		
L13	DATA17	M13	DATA14	N13	DATA11	P13	DATA6		
L14	DATA18	M14	DATA15	N14	NC6	P14	NC5		

Package Outline Dimensions

196-Ball mini-PBGA

Dimensions shown in mm and (inches)



NOTE 1
THE ACTUAL POSITION OF THE BALL POPULATION IS WITHIN 0.150 (0.006) OF ITS IDEAL POSITION RELATIVE TO THE PACKAGE EDGES. THE ACTUAL POSITION OF EACH BALL IS WITHIN 0.05 (0.002) OF ITS IDEAL POSITION RELATIVE TO THE BALL POPULATION.

NOTE 2
ALL MEASUREMENTS ARE PROVIDED IN METRIC AND (ENGLISH) UNITS. BECAUSE THIS IS A METRIC PACKAGE, THE ENGLISH MEASUREMENTS ARE PROVIDED AS A COURTESY. ANALOG DEVICES STRONGLY RECOMMENDS THAT YOU DESIGN WITH THE METRIC MEASUREMENTS ONLY. THE SOLDER BALL MATRIX OF THIS PACKAGE IS 14 X 14

Ordering Guide

The following ordering guide shows all available speed grades and package options for the ADSP-21065L mini BGA. For complete information on these processors visit our web site at <http://www.analog.com/dsp>.

Part Number	Case Temperature Range	Instruction Rate	On-chip SRAM	Operating Voltage	Package Option
ADSP-21065LKCA-240X	0-85°C	60MHz	544-Kbit	3.3V	196 mini BGA